

**XPT IGBT**

$V_{CES} = 1200V$

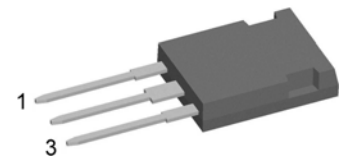
$I_{C25} = 43A$

$V_{CE(sat)} = 1.8V$

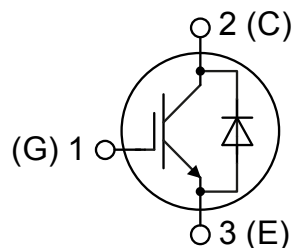
Copack

Part number

IXA27IF1200HJ



Backside: isolated

**Features / Advantages:**

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design (Xtreme light Punch Through) results in:
  - short circuit rated for 10  $\mu$ sec.
  - very low gate charge
  - low EMI
  - square RBSOA @ 3x Ic
- Thin wafer technology combined with the XPT design results in a competitive low VCE(sat)
- SONIC™ diode
  - fast and soft reverse recovery
  - low operating forward voltage

**Applications:**

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies
- Inductive heating, cookers
- Pumps, Fans

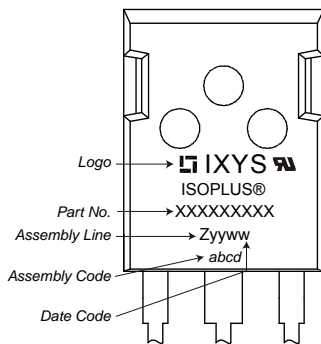
**Package: ISOPLUS247**

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling

IGBT				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{CES}$	collector emitter voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
$V_{GES}$	max. DC gate voltage				$\pm 20$	V	
$V_{GEM}$	max. transient gate emitter voltage				$\pm 30$	V	
$I_{C25}$	collector current	$T_C = 25^{\circ}C$			43	A	
$I_{C80}$		$T_C = 80^{\circ}C$			27	A	
$P_{tot}$	total power dissipation	$T_C = 25^{\circ}C$			150	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 25A; V_{GE} = 15V$		1.8	2.1	V	
				2.1		V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 1mA; V_{GE} = V_{CE}$	5.4	5.9	6.5	V	
$I_{CES}$	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0V$			0.1	mA	
				0.1		mA	
$I_{GES}$	gate emitter leakage current	$V_{GE} = \pm 20V$			500	nA	
$Q_{G(on)}$	total gate charge	$V_{CE} = 600V; V_{GE} = 15V; I_C = 25A$		76		nC	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600V; I_C = 25A$ $V_{GE} = \pm 15V; R_G = 39\Omega$		70		ns	
$t_r$	current rise time		$T_{VJ} = 125^{\circ}C$	40		ns	
$t_{d(off)}$	turn-off delay time		250		ns		
$t_f$	current fall time		100		ns		
$E_{on}$	turn-on energy per pulse		2.5		mJ		
$E_{off}$	turn-off energy per pulse		3		mJ		
<b>RBSOA</b>	reverse bias safe operating area	$V_{GE} = \pm 15V; R_G = 39\Omega$					
$I_{CM}$		$V_{CEmax} = 1200V$			75	A	
<b>SCSOA</b>	short circuit safe operating area	$V_{CEmax} = 900V$					
$t_{sc}$	short circuit duration	$V_{CE} = 900V; V_{GE} = \pm 15V$			10	$\mu s$	
$I_{sc}$	short circuit current	$R_G = 39\Omega; \text{non-repetitive}$		100		A	
$R_{thJC}$	thermal resistance junction to case				0.84	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0.25		K/W	
<b>Diode</b>							
$V_{RRM}$	max. repetitive reverse voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
$I_{F25}$	forward current	$T_C = 25^{\circ}C$			42	A	
$I_{F80}$		$T_C = 80^{\circ}C$			25	A	
$V_F$	forward voltage	$I_F = 30A$			2.20	V	
				1.95		V	
$I_R$	reverse current	$V_R = V_{RRM}$			*	mA	
	* not applicable, see Ices value above				*	mA	
$Q_{rr}$	reverse recovery charge	$V_R = 600V$ $-di_F/dt = -600A/\mu s$ $I_F = 30A; V_{GE} = 0V$		3.5		$\mu C$	
$I_{RM}$	max. reverse recovery current		$T_{VJ} = 125^{\circ}C$	30		A	
$t_{rr}$	reverse recovery time		350		ns		
$E_{rec}$	reverse recovery energy		0.9		mJ		
$R_{thJC}$	thermal resistance junction to case				1.2	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0.25		K/W	

Package ISOPLUS247		Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			70	A
$T_{VJ}$	virtual junction temperature		-40		150	°C
$T_{op}$	operation temperature		-40		125	°C
$T_{stg}$	storage temperature		-40		150	°C
<b>Weight</b>				6		g
$F_C$	mounting force with clip		20		120	N
$d_{Spp/App}$	creepage distance on surface   striking distance through air	terminal to terminal	2.7			mm
$d_{Spbl/Apb}$		terminal to backside	4.1			mm
$V_{ISOL}$	isolation voltage	t = 1 second	3600			V
		t = 1 minute	3000			V

### Product Marking



### Part number

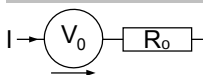
I = IGBT  
 X = XPT IGBT  
 A = Gen 1 / std  
 27 = Current Rating [A]  
 IF = Copack  
 1200 = Reverse Voltage [V]  
 HJ = ISOPLUS247 (3)

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	IXA27IF1200HJ	IXA27IF1200HJ	Tube	30	509098

### Equivalent Circuits for Simulation

\* on die level

$T_{VJ} = 150\text{ °C}$

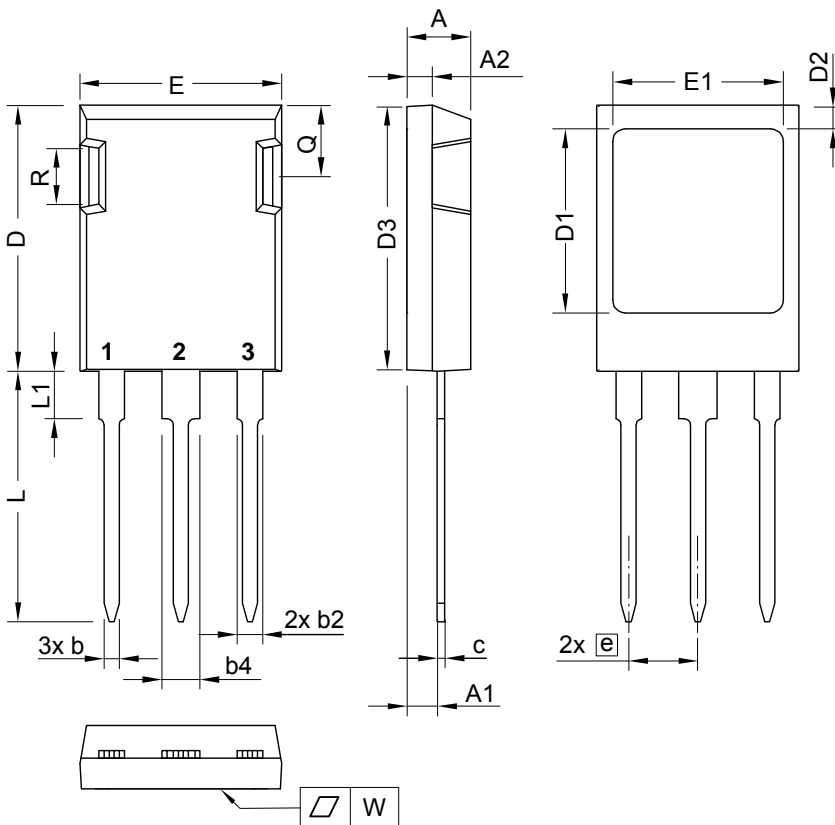


$V_{0\max}$  threshold voltage

$R_{0\max}$  slope resistance \*

	IGBT	Diode	
$V_{0\max}$	1.1	1.25	V
$R_{0\max}$	55	28.3	mΩ

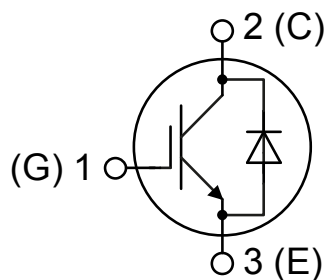
## Outlines ISOPLUS247



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.29	2.54	0.090	0.100
A2	1.91	2.16	0.075	0.085
b	1.14	1.40	0.045	0.055
b2	1.91	2.20	0.075	0.087
b4	2.92	3.24	0.115	0.128
c	0.61	0.83	0.024	0.033
D	20.80	21.34	0.819	0.840
D1	15.75	16.26	0.620	0.640
D2	1.65	2.15	0.065	0.085
D3	20.30	20.70	0.799	0.815
E	15.75	16.13	0.620	0.635
E1	13.21	13.72	0.520	0.540
e	5.45 BSC		0.215 BSC	
L	19.81	20.60	0.780	0.811
L1	3.81	4.38	0.150	0.172
Q	5.59	6.20	0.220	0.244
R	4.25	5.50	0.167	0.217
W	-	0.10	-	0.004

Die konvexe Form des Substrates ist typ. < 0.04 mm über der Kunststoffoberfläche der Bauteilunterseite  
 The convex bow of substrate is typ. < 0.04 mm over plastic surface level of device bottom side

Die Gehäuseabmessungen entsprechen dem Typ TO-247 AD gemäß JEDEC außer Schraubloch und  $L_{max}$ .  
 This drawing will meet all dimensions requirement of JEDEC outline TO-247 AD except screw hole and except  $L_{max}$ .



## IGBT

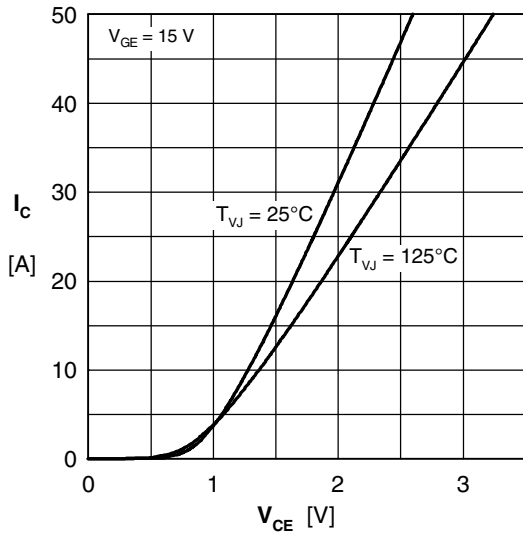


Fig. 1 Typ. output characteristics

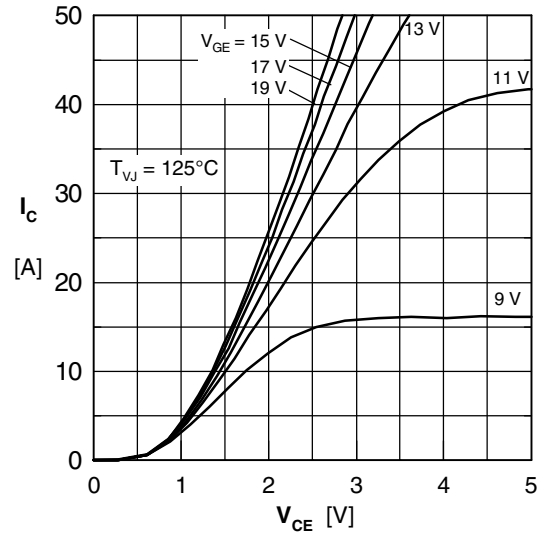


Fig. 2 Typ. output characteristics

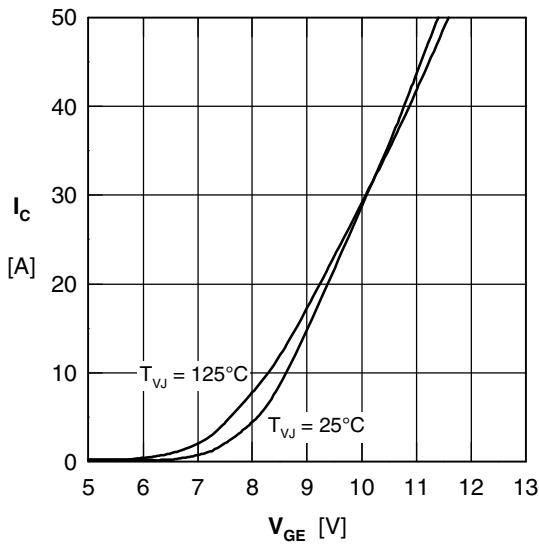


Fig. 3 Typ. transfer characteristics

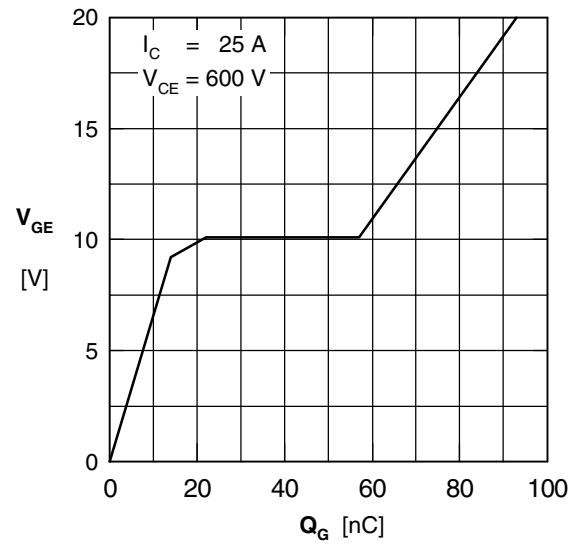


Fig. 4 Typ. turn-on gate charge

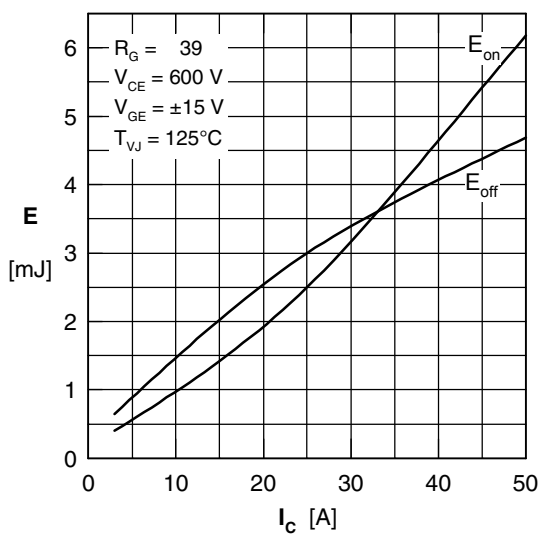


Fig. 5 Typ. switching energy vs. collector current

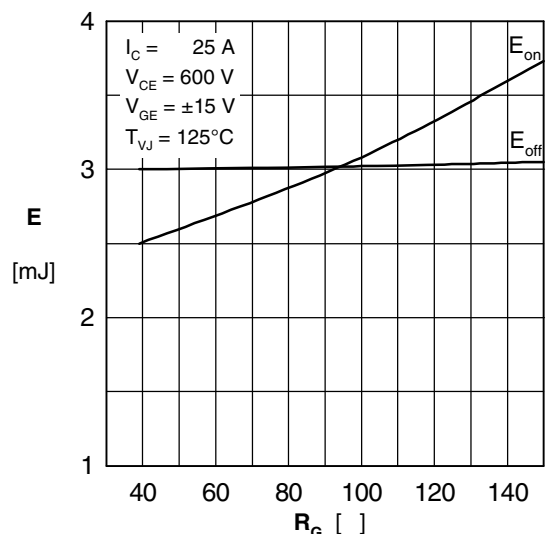


Fig. 6 Typ. switching energy vs. gate resistance

## Diode

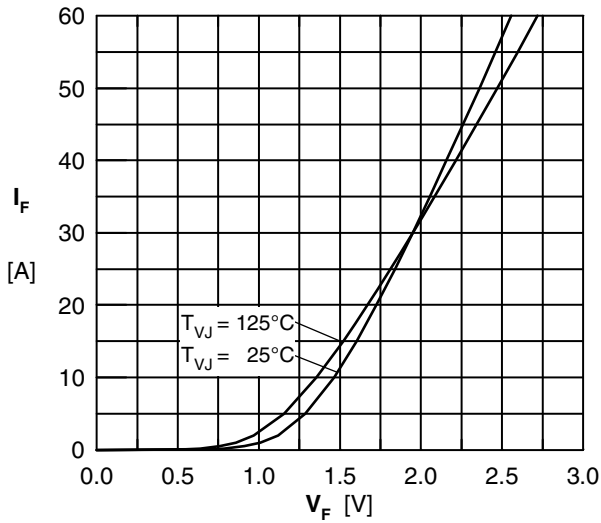


Fig. 7 Typ. Forward current versus  $V_F$

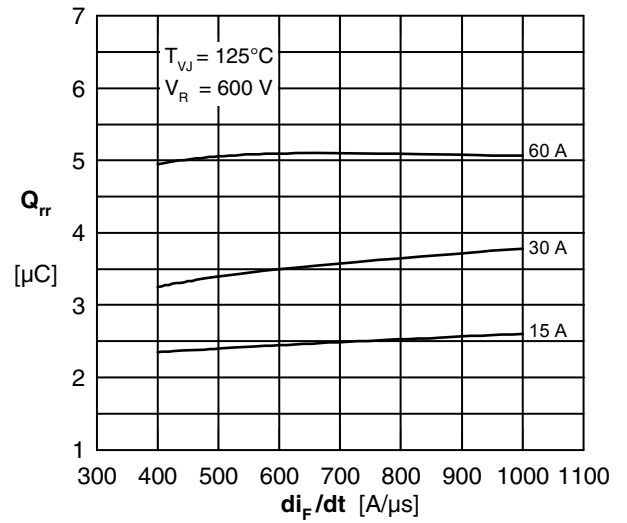


Fig. 8 Typ. reverse recov. charge  $Q_{rr}$  vs.  $di/dt$

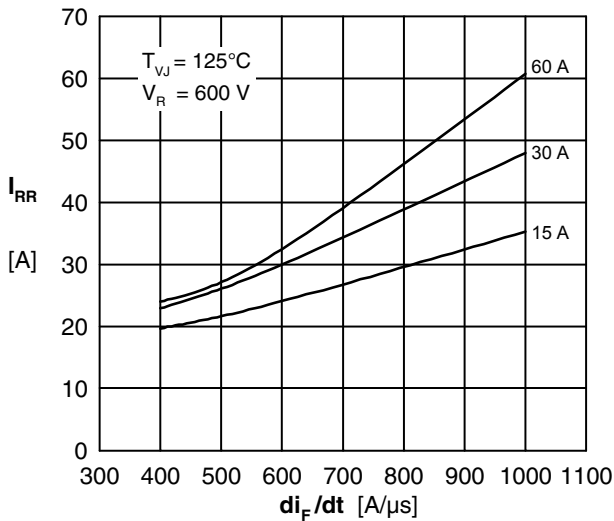


Fig. 9 Typ. peak reverse current  $I_{RM}$  vs.  $di/dt$

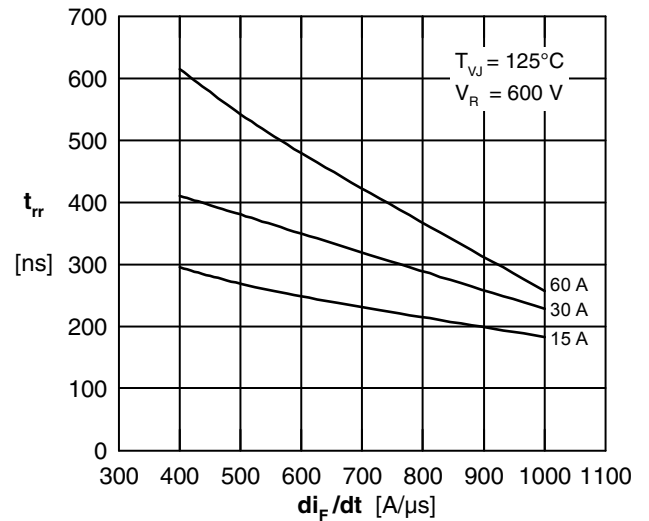


Fig. 10 Typ. recovery time  $t_{rr}$  versus  $di/dt$

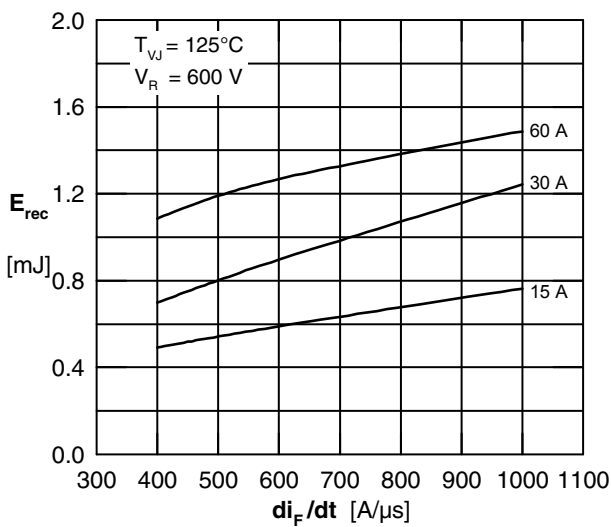


Fig. 11 Typ. recovery energy  $E_{rec}$  versus  $di/dt$

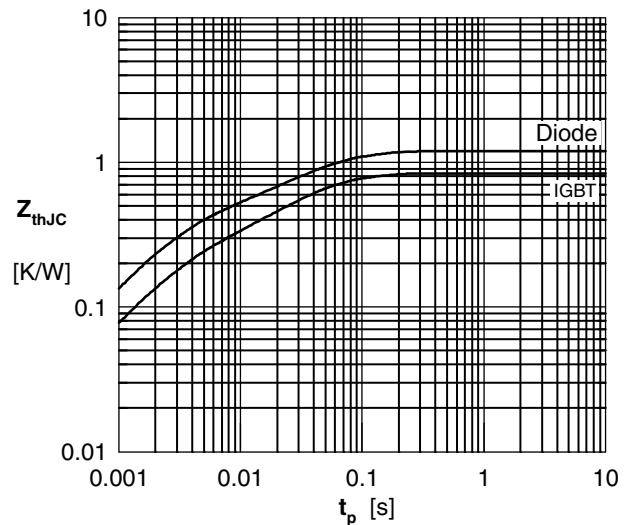


Fig. 12 Typ. transient thermal impedance



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